

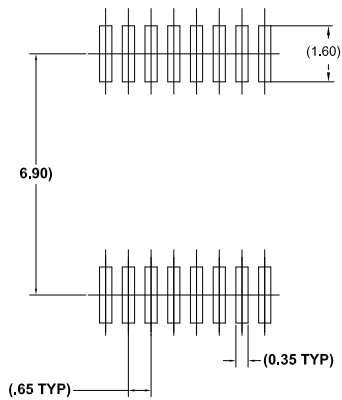
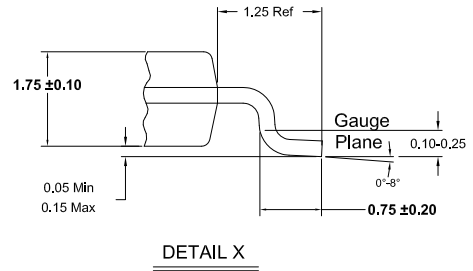
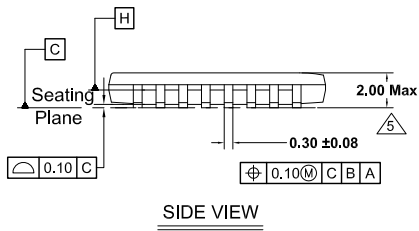
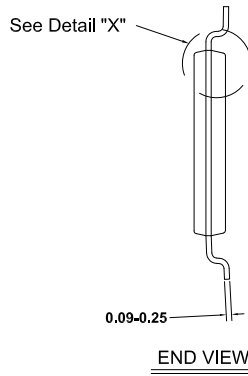
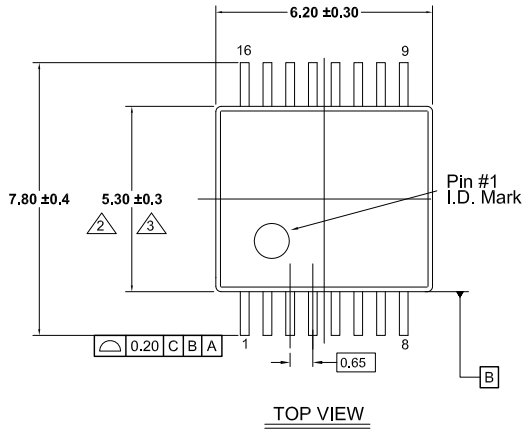
# Plastic Packages for Integrated Circuits

## Package Outline Drawing

M16.209

16 Lead Shrink Small Outline Plastic Package (SSOP)

Rev 4, 3/2022



**Notes:**

- (1) Dimension does not include mold flash, protrusions or gate burrs. Mold flash, protrusions or gate burrs shall not exceed 0.15 per side.
- (2) Dimension does not include interlead flash or protrusion. Interlead flash or protrusion shall not exceed 0.25 per side.
- (3) Dimensions are measured at datum plane H.
- (4) Dimensioning and tolerancing per ASME Y14.5M-1994.
- (5) Dimension does not include dambar protrusion. Allowable protrusion shall be 0.80mm total in excess of dimension at maximum material condition. Minimum space between protrusion and adjacent lead is 0.07mm.
- (6) Dimension in ( ) are for reference only.
- (7) Conforms to JEDEC MO-153.